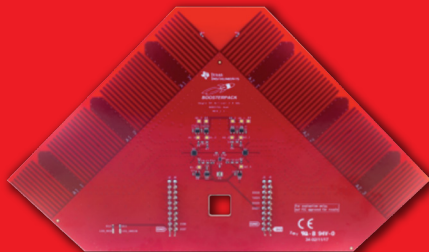




Angle of Arrival BoosterPack™

plug-in module for the TI LaunchPad™
Development ecosystem

PART NO: BOOSTXL-AOA



BOOST
YOUR DESIGN

START @
ti.com/BOOSTXL-AOA

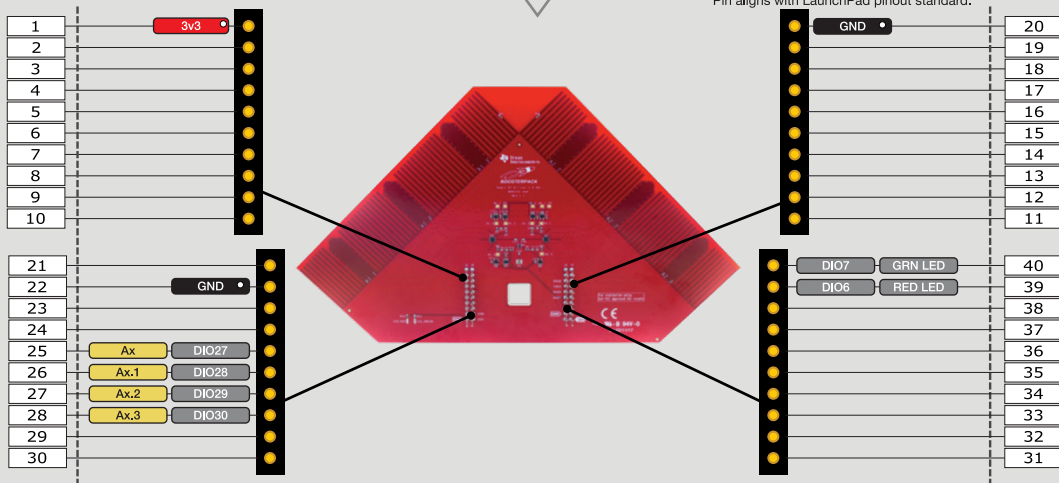


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○ Make your own BoosterPack @ www.ti.com/byob
Pin aligns with LaunchPad pinout standard.



Explore all TI BoosterPack™ modules @ ti.com/boosterpacks

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